

April 1, 2021

Design Metrics

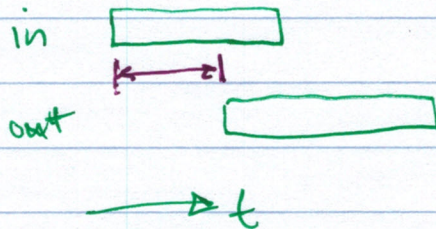
1) Energy per operation

Ex: Joules per JPEG image compressed

2) Performance

a) Throughput

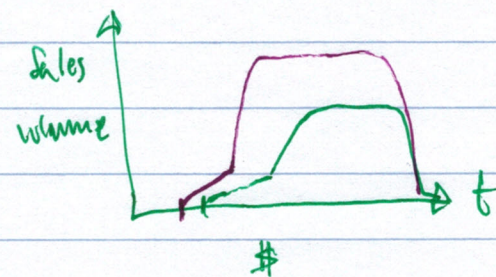
Ex: 250 M Samples/sec

(high)  
betterb) Latency time from first data in  $\rightarrow$  ~~last~~ <sup>first!</sup> data out(low)  
better

c) Numerical precision

3) Circuit area (resources)

4) Design complexity

design time  $\rightarrow$  "time to market"

5) Suitable for future fab. technologies

- More transistors

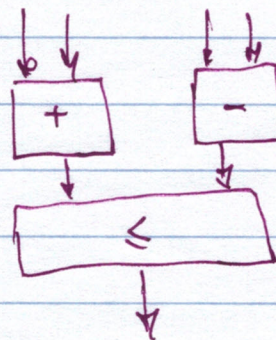
- More faults

⋮

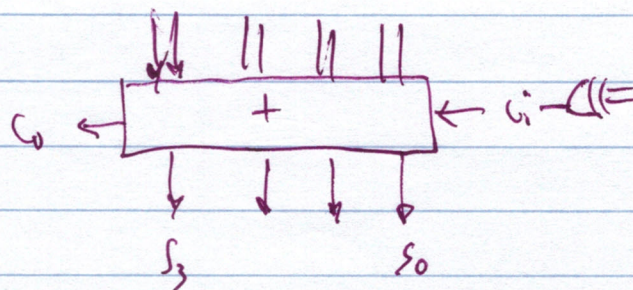
↑  
fabrication

7 diagrams

1) Block diagram

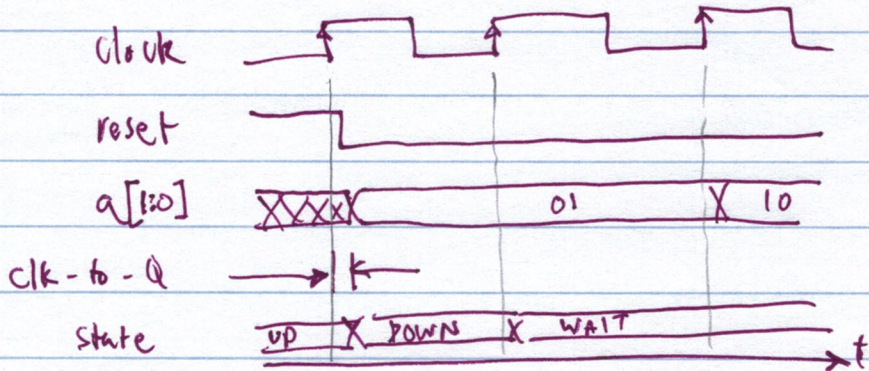


2) Circuit diagram  
- more detail than block

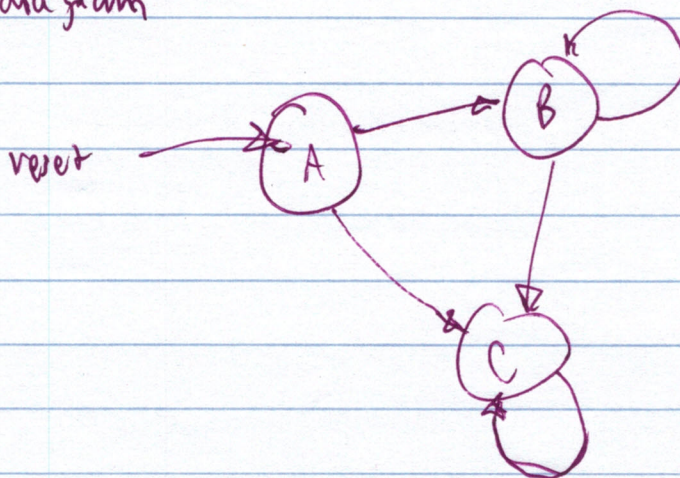


3) Timing

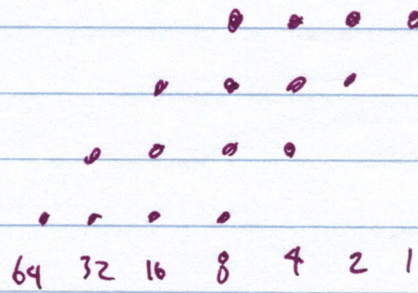
logic level vs. time



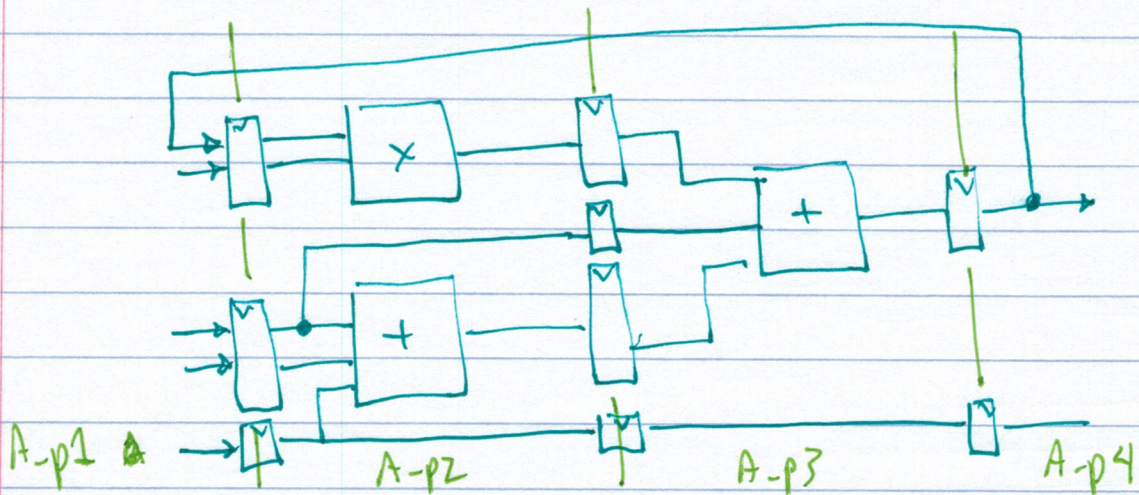
4) State diagram



### 5) Arithmetic dot diagram

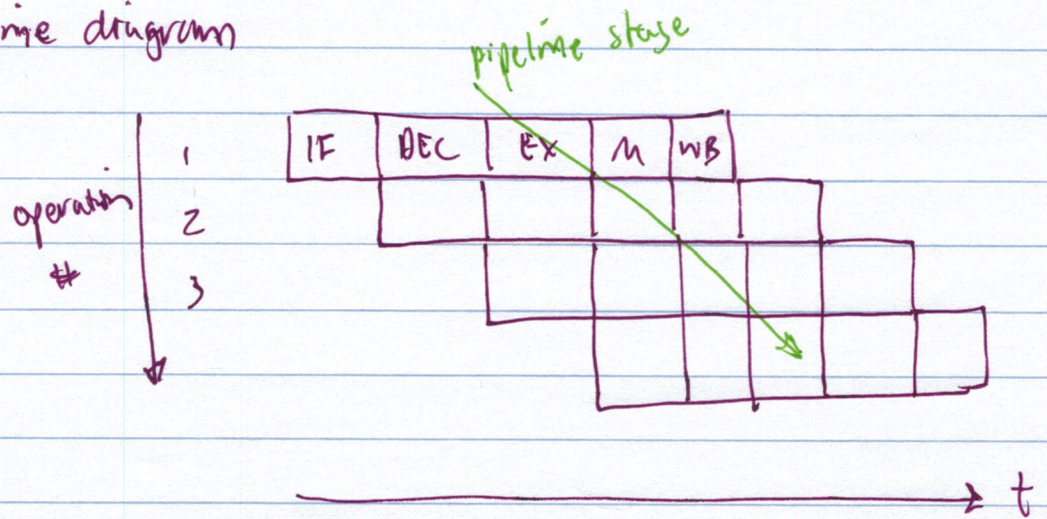


### 6) Pipelined Block diagram



- All registers aligned
- "Reverse" flowing signals need not be registered

### 7) Pipeline diagram



O.H. Mon 4-5 Apr. 5

Chip Design Methodologies

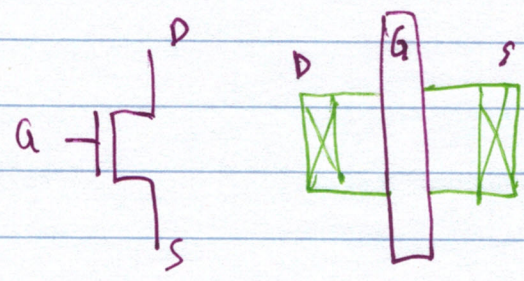
1) Full Custom - \$50M one-time cost  
 highest perf.  
 lowest energy/op.  
 lowest cost per part

6) Programmable general purpose  
 lowest design time  
 lower one-time cost



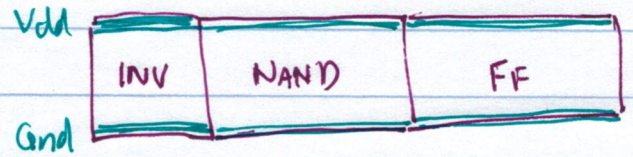
VLSI - Very large scale Integration  
 - "semiconductor chip"

1) Full custom



- analog

- 2) Standard cell  
- same height



- can be "placed & routed" by computer

- 3) Gate Array

- customized with metal layers

- 4) Field-Programmable Gate Array - FPGA

- customized with config bits

- 5) Prog. Special-purpose

- DSP  
- GPUs

- 6) Prog. General-purpose

- Intel  
- AMD  
- ARM

